

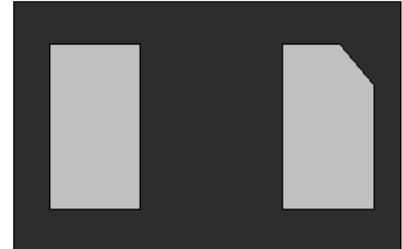


### FEATURES

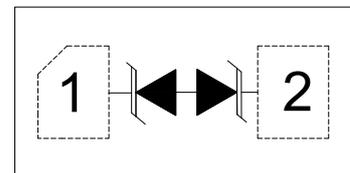
- ✧ Solid-state silicon technology
- ✧ Low clamping voltage and low leakage current
- ✧ Working voltage: 4.5V
- ✧ Ultra-low capacitance
- ✧ RoHS compliant

### MAIN APPLICATIONS

- ✧ Cellular handsets
- ✧ Tablets
- ✧ Laptops
- ✧ Network communication devices
- ✧ Other portable devices



DFN1006-2L (Bottom view)



Pin Configuration (Top view)

### PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 27A (8/20µs)

### MECHANICAL CHARACTERISTICS

- ✧ DFN1006-2L package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Marking code: 4G
- ✧ Quantity per reel: 10,000pcs
- ✧ Lead finish: lead free

### ABSOLUTE MAXIMUM RATINGS(T<sub>A</sub>=25°C, RH=45%-75%, unless otherwise noted)

| Parameter                                       | Symbol           | Value         | Unit |
|---|------------------|---------------|------|
| Peak pulse power dissipation at 8/20µs waveform | P <sub>PP</sub>  | 300           | W    |
| ESD per IEC 61000-4-2 (Air)                     | V <sub>ESD</sub> | +/- 30        | kV   |
| ESD per IEC 61000-4-2 (Contact)                 |                  | +/- 30        |      |
| Lead soldering temperature                      | T <sub>L</sub>   | 260 (10 sec.) | °C   |
| Operating junction temperature range            | T <sub>J</sub>   | -55 to +125   | °C   |
| Storage temperature range                       | T <sub>STG</sub> | -55 to +150   | °C   |

ELECTRICAL CHARACTERISTICS( $T_A=25^{\circ}\text{C}$ )

| Parameter                 | Symbol        | Conditions                                  | Min | Typ  | Max | Unit          |
|---------------------------|---------------|---|-----|------|-----|---------------|
| Reverse working voltage   | $V_{RWM}$     |   |     |      | 4.5 | V             |
| Reverse breakdown voltage | $V_{BR}$      | $I_T=1\text{mA}$                            | 4.6 |      |     | V             |
| Reverse leakage current   | $I_R$         | $V_{RWM}=4.5\text{V}$                       |     |      | 1.0 | $\mu\text{A}$ |
| Peak pulse current        | $I_{PP}$      | $t_P=8/20\mu\text{s}$                       |     |      | 27  | A             |
| Clamping voltage          | $V_C^{①}$     | $I_{PP}=16\text{A}$ , $t_P=100\text{ns}$    |     | 7    |     | V             |
| Dynamic resistance        | $R_{DYN}^{①}$ |   |     | 0.09 |     | $\Omega$      |
| Clamping voltage          | $V_C^{②}$     | $V_{ESD}=8\text{kV}$                        |     | 9    |     | V             |
| Clamping voltage          | $V_C^{③}$     | $I_{PP}=1\text{A}$ , $t_P=8/20\mu\text{s}$  |     | 5    | 6   | V             |
|                           |               | $I_{PP}=20\text{A}$ , $t_P=8/20\mu\text{s}$ |     | 8    | 9.5 | V             |
|                           |               | $I_{PP}=27\text{A}$ , $t_P=8/20\mu\text{s}$ |     | 10   | 11  | V             |
| Junction capacitance      | $C_J$         | $V_{RWM}=0\text{V}$ , $f=1\text{MHz}$       |     | 80   | 95  | pF            |

- ① TLP parameter:  $Z_0=50\Omega$ ,  $t_P=100\text{ns}$ ,  $t_r=2\text{ns}$ , averaging window from 60ns to 80ns.  $R_{DYN}$  is calculated from 4A to 16A.
- ② Contact discharge mode, according to IEC61000-4-2.
- ③ Non-repetitive current pulse, according to IEC61000-4-5.

RATINGS AND V-I CHARACTERISTICS CURVES (T<sub>A</sub>=25°C, unless otherwise noted)

FIG.1: V- I curve characteristics (Bi-directional)

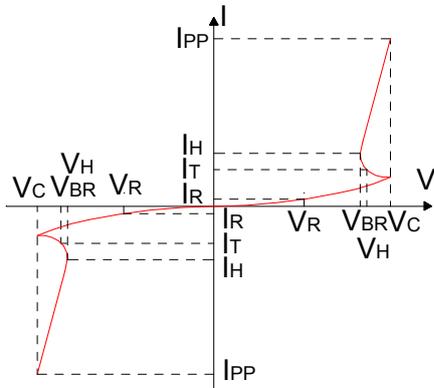


FIG.2: Pulse waveform (8/20μs)

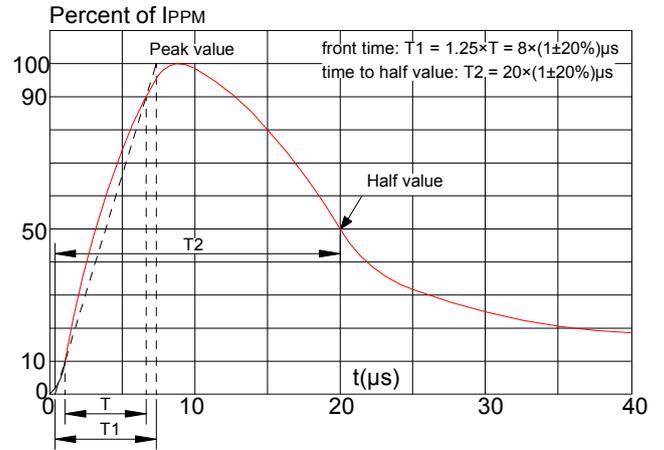


FIG.3: Pulse derating curve

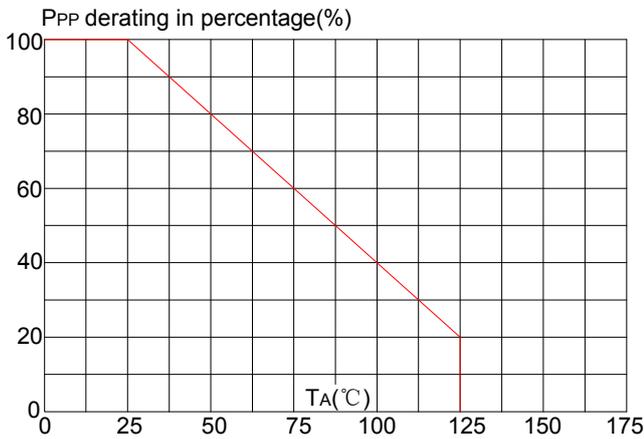


FIG.4: ESD clamping (30kV contact)

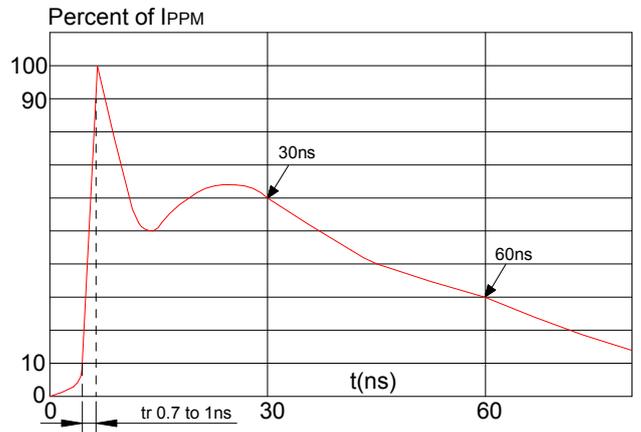


FIG.5: Clamping voltage vs. peak pulse current

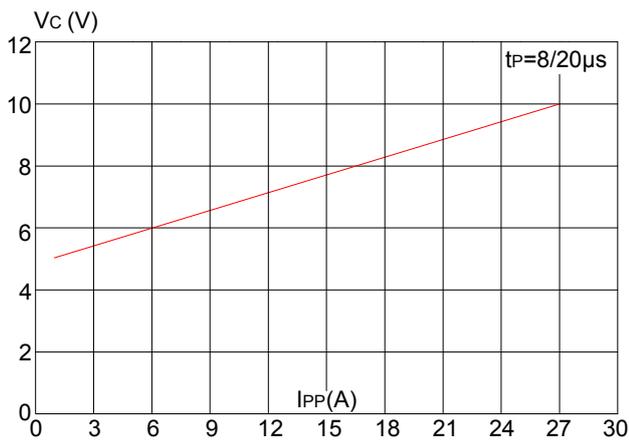
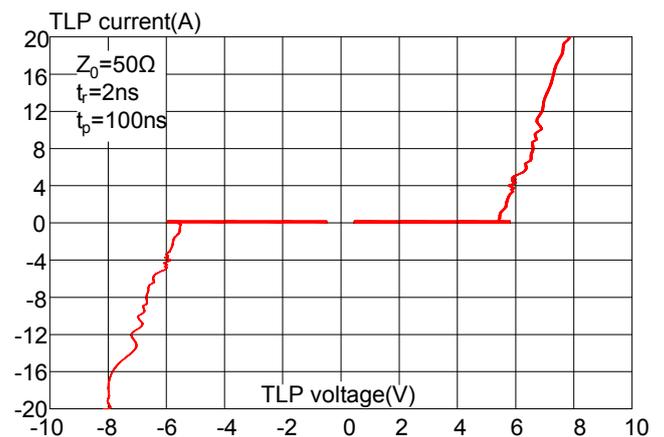
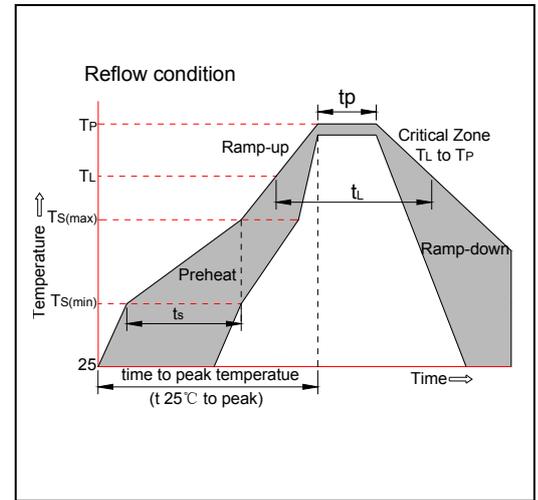


FIG.6: TLP Measurement

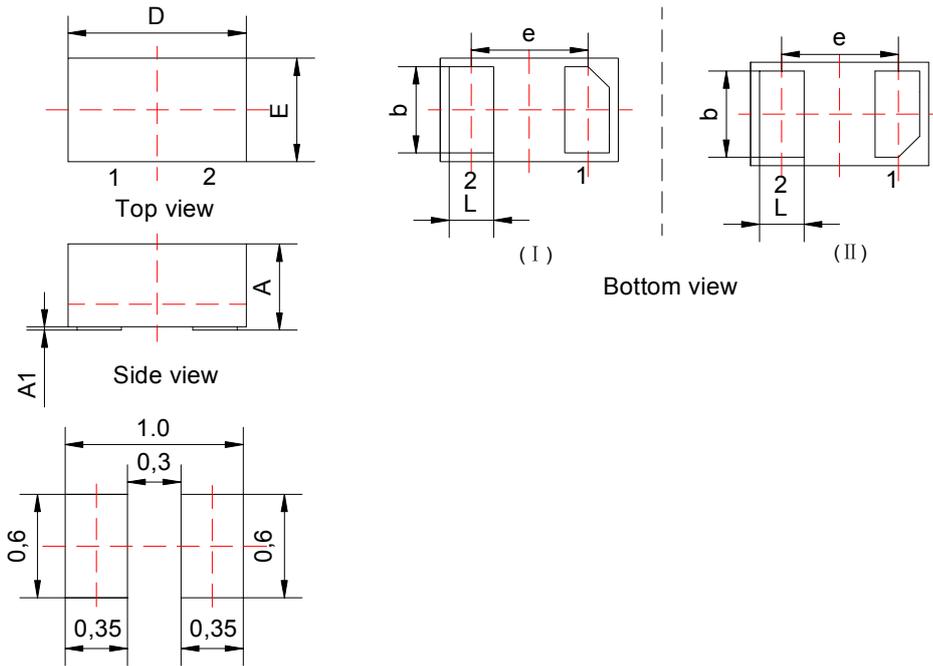


**SOLDERING PARAMETERS**

|   |                                   |   |
|---|-----------------------------------|---|
| Reflow Condition                                      |                                   | Pb-Free assembly<br>(see figure at right) |
| Pre Heat  | -Temperature Min ( $T_{s(min)}$ ) | +150°C                                    |
|   | -Temperature Max( $T_{s(max)}$ )  | +200°C                                    |
|   | -Time (Min to Max) ( $t_s$ )      | 60-180 secs.                              |
| Average ramp up rate (Liquidus Temp ( $T_L$ )to peak) |                                   | 3°C/sec. Max                              |
| $T_{s(max)}$ to $T_L$ - Ramp-up Rate                  |                                   | 3°C/sec. Max                              |
| Reflow  | -Temperature( $T_L$ )(Liquidus)   | +217°C                                    |
|   | -Temperature( $t_L$ )             | 60-150 secs.                              |
| Peak Temp ( $T_p$ )                                   |                                   | +260(+0/-5)°C                             |
| Time within 5°C of actual Peak Temp ( $t_p$ )         |                                   | 20-40secs.                                |
| Ramp-down Rate  |                                   | 6°C/sec. Max                              |
| Time 25°C to Peak Temp ( $T_p$ )                      |                                   | 8 min. Max                                |
| Do not exceed   |                                   | +260°C                                    |



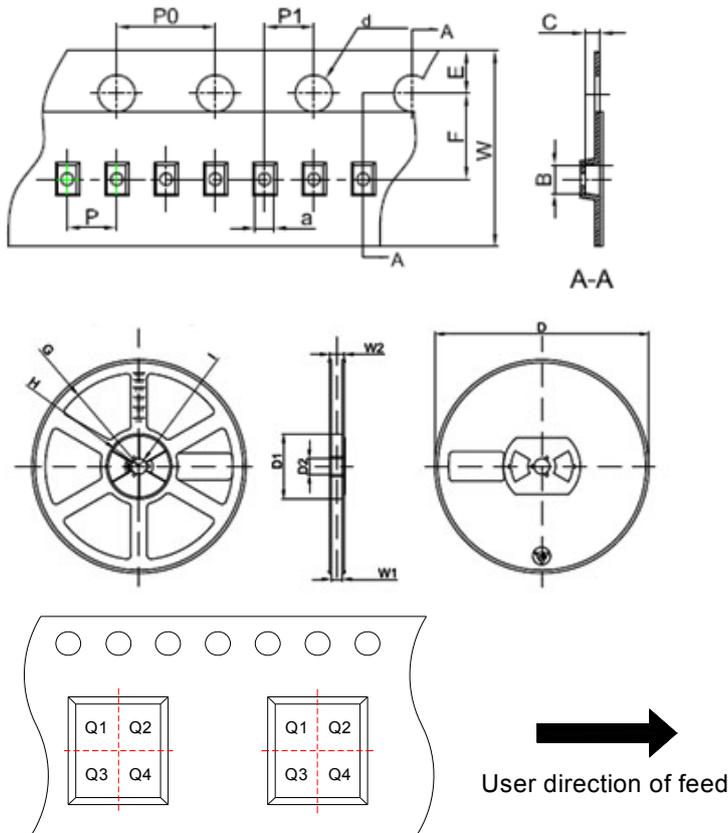
**PACKAGE MECHANICAL DATA**



Recommended soldering footprint(mm)

| Symbol | Millimeters |      |      | Inches   |       |       |
|--------|-------------|------|------|----------|-------|-------|
|        | Min.        | Typ. | Max. | Min.     | Typ.  | Max.  |
| A      | 0.40        | 0.50 | 0.55 | 0.016    | 0.020 | 0.022 |
| A1     | 0.00        | 0.02 | 0.05 | 0.000    | 0.001 | 0.002 |
| b      | 0.45        | 0.50 | 0.55 | 0.018    | 0.020 | 0.022 |
| D      | 0.95        | 1.00 | 1.05 | 0.037    | 0.039 | 0.041 |
| e      | 0.65BSC     |      |      | 0.026BSC |       |       |
| E      | 0.55        | 0.60 | 0.65 | 0.022    | 0.024 | 0.026 |
| L      | 0.20        | 0.25 | 0.30 | 0.008    | 0.010 | 0.012 |

**TAPE AND REEL INFORMATION-DFN1006-2L**



Pin 1 quadrant:Q1&Q2

**Packaging Description:**

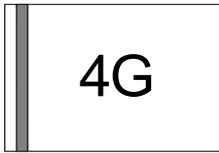
DFN1006-2L parts are shipped in tape. The carrier tape is made from a dissipative(carbon filled) polycarbonate resin. The cover tape is a multilayer film(heat activated adhesive in nature)primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 10,000units per 7" or 17.8cm diameter reel. The reels are clear in color and made of polystyrene plastic(anti-static

| Symbol | Millimeters | Inches |
|--------|-------------|--------|
|        | Typ.        | Typ.   |
| a      | 0.66        | 0.026  |
| B      | 1.15        | 0.045  |
| C      | 0.66        | 0.026  |
| d      | Φ1.50       | Φ0.059 |
| E      | 1.75        | 0.069  |
| F      | 3.50        | 0.138  |
| P0     | 4.00        | 0.157  |
| P      | 2.00        | 0.079  |
| P1     | 2.00        | 0.079  |
| W      | 8.00        | 0.315  |
| D      | Φ178        | Φ7.008 |
| D1     | 54.40       | 2.142  |
| D2     | 13.00       | 0.512  |
| G      | R78.00      | R3.071 |
| H      | R25.60      | R1.008 |
| I      | R6.50       | R0.256 |
| W1     | 9.50        | 0.374  |
| W2     | 12.30       | 0.484  |

**ORDERING INFORMATION**

| PART No.  | PACKAGE TYPE | QUANTITY(PCS) REEL | DESCRIPTION      |
|-----------|--------------|--------------------|------------------|
| JEB4V5DFP | DFN1006-2L   | 10,000             | 7 inch reel pack |

**MARKING CODE**

| Part Number | Marking Code   |
|-------------|--|
| JEB4V5DFP   |  |

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